### Hex, Low Skew, 1-to-2 Differential-to-3.3V/2.5V LVPECL Clock Buffer

### GENERAL DESCRIPTION



The ICS8537-01 is a Hex low skew, high performance 1-to-2 Differential-to-3.3V/2.5 LVPECL Clock Buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The ICS8537-01 has six selectable clock in-

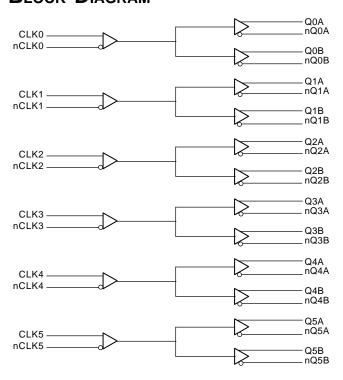
puts. The CLKx, nCLKx pairs can accept most differential input levels and translate them to 3.3V or 2.5V LVPECL output levels.

Guaranteed output and part-to-part skew specifications make the ICS8537-01 ideal for those applications demanding well defined performance and repeatability.

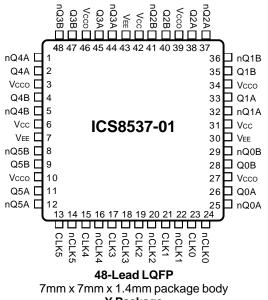
### **F**EATURES

- 12 LVPECL outputs
- Selectable differential CLKx, nCLKx inputs
- CLKx, nCLKx pair can accept the following differential input levels: LVPECL, LVDS, LVHSTL, HCSL, SSTL
- Maximum output frequency: 700MHz
- Translates any differential input signal (LVHSTL, SSTL, DCM) to LVPECL levels without external bias networks
- Translates any single-ended input signal to LVPECL with resistor bias on nCLKx input
- Output skew: 130ps (maximum)
- Bank skew: 20ps (maximum)
- Part-to-part skew: 350ps (maximum)
- Propagation delay: 1.5ns (maximum)
- 3.3V or 2.5V operating supply
- 0°C to 85°C ambient operating temperature
- Industrial temperature information available upon request

### **BLOCK DIAGRAM**



### PIN ASSIGNMENT



7mm x 7mm x 1.4mm package body
Y Package
Top View

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TABLE 1. PIN DESCRIPTIONS

Number	Name	Т	уре	Description
1, 2	nQ4A, Q4A	Output		Differential output pair. LVPECL interface levels.
3, 10, 27, 34, 39, 46	V <sub>cco</sub>	Power		Output supply pins.
4, 5	Q4B, nQ4B	Output		Differential output pair. LVPECL interface levels.
6, 31, 42	V <sub>cc</sub>	Power		Core supply pins.
7, 30, 43	$V_{_{EE}}$	Power		Negative supply pins.
8, 9	nQ5B, Q5B	Output		Differential output pair. LVPECL interface levels.
11, 12	Q5A, nQ5A	Output		Differential output pair. LVPECL interface levels.
13	CLK5	Input	Pullup	Inverting differential clock input.
14	nCLK5	Input	Pulldown	Non-inverting differential clock input.
15	CLK4	Input	Pullup	Non-inverting differential clock input.
16	nCLK4	Input	Pulldown	Inverting differential clock input.
17	CLK3	Input	Pullup	Non-inverting differential clock input.
18	nCLK3	Input	Pulldown	Inverting differential clock input.
19	CLK2	Input	Pullup	Non-inverting differential clock input.
20	nCLK2	Input	Pulldown	Inverting differential clock input.
21	CLK1	Input	Pullup	Non-inverting differential clock input.
22	nCLK1	Input	Pulldown	Inverting differential clock input.
23	CLK0	Input	Pullup	Non-inverting differential clock input.
24	nCLK0	Input	Pulldown	Inverting differential clock input.
25, 26	nQ0A, Q0A	Output		Differential output pair. LVPECL interface levels.
28, 29	Q0B, nQ0B	Output		Differential output pair. LVPECL interface levels.
32, 33	nQ1A, Q1A	Output		Differential output pair. LVPECL interface levels.
35, 36	Q1B, nQ1B	Output		Differential output pair. LVPECL interface levels.
37, 38	nQ2A, Q2A	Output		Differential output pair. LVPECL interface levels.
40, 41	Q2B, nQ2B	Output		Differential output pair. LVPECL interface levels.
44, 45	nQ3A, Q3A	Output		Differential output pair. LVPECL interface levels.
47, 48	Q3B, nQ3B	Output		Differential output pair. LVPECL interface levels.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

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### TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance				4	pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		ΚΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		KΩ

### TABLE 3. CLOCK INPUT FUNCTION TABLE

Inputs		Ou	tputs			
CLKx	nCLKx	Q0A:Q5A, Q0B:Q5B	nQ0A:nQ5A, nQ5B:nQ5B	Input to Output Mode	Polarity	
0	1	LOW	HIGH	Differential to Differential	Non Inverting	
1	0	HIGH	LOW	Differential to Differential	Non Inverting	
0	Biased; NOTE 1	LOW	HIGH	Single Ended to Differential	Non Inverting	
1	Biased; NOTE 1	HIGH	LOW	Single Ended to Differential	Non Inverting	
Biased; NOTE 1	0	HIGH	LOW	Single Ended to Differential	Inverting	
Biased; NOTE 1	1	LOW	HIGH	Single Ended to Differential	Inverting	

NOTE 1: Please refer to the Application Information section, "Wiring the Differential Input to Accept Single ended levels".



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### ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V<sub>CC</sub> 4.6V

Inputs,  $V_1$  -0.5V to  $V_{cc}$  + 0.5 V

Outputs,  $V_{O}$  -0.5V to  $V_{CCO}$  + 0.5V

Package Thermal Impedance,  $\theta_{JA}$  47.9°C/W (0 Ifpm)

Storage Temperature, T<sub>STG</sub> -65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 4A. Power Supply DC Characteristics,  $V_{\rm CC} = V_{\rm CCO} = 2.375 V$  to 3.465 V, Ta = 0°C to  $85 ^{\circ}$ C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>cc</sub>	Core Supply Voltage		2.375	3.3	3.465	V
V <sub>cco</sub>	Output Supply Voltage		2.375	3.3	3.465	V
I <sub>EE</sub>	Power Supply Current				130	mA

**Table 4B. Differential DC Characteristics,**  $V_{cc} = V_{cco} = 2.375V$  to 3.465V,  $T_A = 0$ °C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
	Input High Current	CLKx	$V_{IN} = V_{CC} = 3.465V$			150	μΑ
I <sub>IH</sub>		nCLKx	$V_{IN} = V_{CC} = 3.465V$			5	μΑ
	Input Low Current	CLKx	$V_{CC} = 3.465V, V_{IN} = 0V$	-5			μΑ
I'IL	Input Low Current	nCLKx	$V_{CC} = 3.465V, V_{IN} = 0V$	-150			μΑ
V <sub>PP</sub>	Peak-to-Peak Voltag	ge		0.15		1.3	V
V <sub>CMR</sub>	Common Mode Volt	tage; NOTE 1, 2		V <sub>EE</sub> + 0.5		V <sub>cc</sub> - 0.85	V

NOTE 1: For single ended appliations, the maximum input voltage for CLK, nCLK is  $V_{cc}$  + 0.3V.

NOTE 2: Common mode voltage is defined as  $V_{H}$ .

Table 4C. LVPECL DC Characteristics,  $V_{cc} = V_{cco} = 2.375 \text{V}$  to 3.465 V, Ta = 0°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>OH</sub>	Output High Voltage; NOTE 1		V <sub>cco</sub> - 1.4		V <sub>cco</sub> - 1.0	V
V <sub>OL</sub>	Output Low Voltage; NOTE 1		V <sub>cco</sub> - 2.0		V <sub>cco</sub> - 1.7	V
V <sub>SWING</sub>	Peak-to-Peak Output Voltage Swing		0.6		1.0	V

NOTE 1: Outputs terminated with 50  $\!\Omega$  to  ${\rm V_{CCO}}$  - 2V.

### ICS8537-01

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Table 5. AC Characteristics,  $V_{CC} = V_{CCO} = 2.375 V$  to 3.465 V,  $T_A = 0 ^{\circ} C$  to  $85 ^{\circ} C$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency				700	MHz
t <sub>PD</sub>	Propagation Delay; NOTE 1	<i>f</i> ≤ 700MHz	1.1	1.3	1.5	ns
tsk(o)	Output Skew; NOTE 2, 5				130	ps
tsk(b)	Bank Skew; NOTE 3, 5				20	ps
tsk(pp)	Part-to-Part Skew; NOTE 4, 5				350	ps
t <sub>R</sub> / t <sub>F</sub>	Output Rise/Fall Time	20% to 80%	200		600	ps
odo	Output Duty Cycle	<i>f</i> ≤ 300MHz	47		53	%
odc	Output Duty Cycle	<i>f</i> > 300MHz, <i>f</i> ≤ 500MHz	45		55	%

All parameters measured at 500MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltages and with equal load conditions.

Measured from at the output differential cross points.

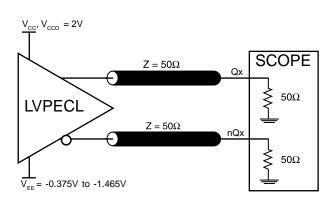
NOTE 3: Defined as skew within a bank of outputs at the same voltages and with equal load conditions.

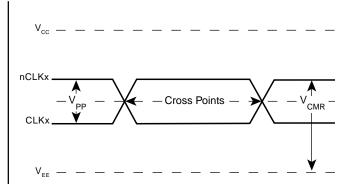
NOTE 4: Defined as between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

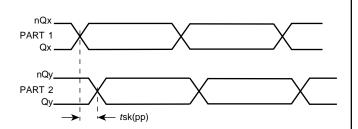


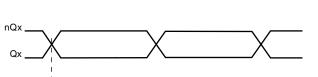
## PARAMETER MEASUREMENT INFORMATION



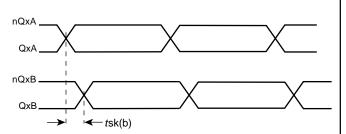


### **OUTPUT LOAD AC TEST CIRCUIT**



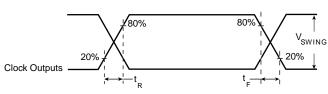


### PART-TO-PART SKEW

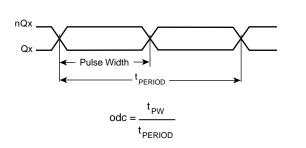


### **OUTPUT SKEW**

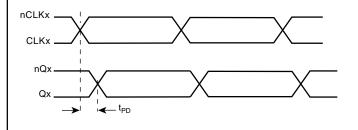
DIFFERENTIAL INPUT LEVEL



### BANK SKEW



### **OUTPUT RISE/FALL TIME**



### odc & t<sub>PERIOD</sub>

### PROPAGATION DELAY

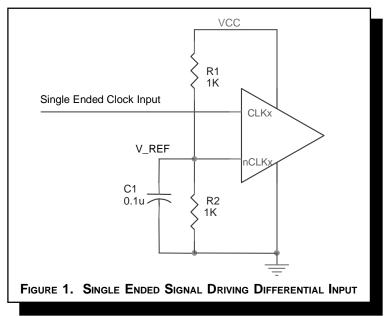
# HEX, LOW SKEW, 1-TO-2 DIFFERENTIAL-TO-3.3V/2.5V LVPECL CLOCK BUFFER

### **APPLICATION INFORMATION**

#### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_REF = V_{CC}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the V\_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{\rm CC}$  = 3.3V, V\_REF should be 1.25V and R2/R1 = 0.609.



### TERMINATION FOR LVPECL OUTPUTS

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive

 $50\Omega$  transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. Figures 2A and 2B show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

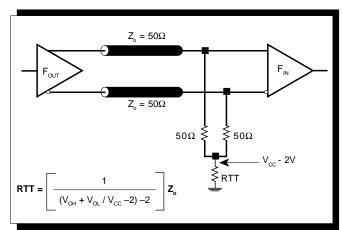


FIGURE 2A. LVPECL OUTPUT TERMINATION

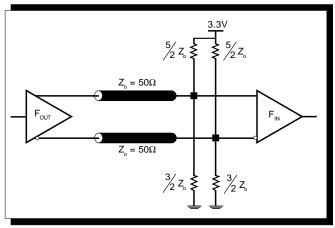


FIGURE 2B. LVPECL OUTPUT TERMINATION

# DIFFERENTIAL-TO-3.3V/2.5V LVPECL CLOCK BUFFER

### Power Considerations

This section provides information on power dissipation and junction temperature for the ICS8537-01. Equations and example calculations are also provided.

#### 1. Power Dissipation.

The total power dissipation for the ICS8537-01 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for  $V_{CC} = 3.3V + 5\% = 3.465V$ , which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)<sub>MAX</sub> = V<sub>CC MAX</sub> \* I<sub>EE MAX</sub> = 3.465V \* 130mA = 450.5mW
- Power (outputs)<sub>MAX</sub> = 30.2mW/Loaded Output pair
   If all outputs are loaded, the total power is 12 \* 30.2mW = 362.4mW

Total Power MAX (3.465V, with all outputs switching) = 450.5mW + 362.4mW = 812.9mW

### 2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for Tj is as follows:  $Tj = \theta_{JA} * Pd_{total} + T_{A}$ 

Tj = Junction Temperature

 $\theta_{1A}$  = junction-to-ambient thermal resistance

Pd\_total = Total device power dissipation (example calculation is in section 1 above)

 $T_A = Ambient Temperature$ 

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 42.1°C/W per Table 6 below.

Therefore, Tj for an ambient temperature of  $70^{\circ}$ C with all outputs switching is:  $70^{\circ}$ C + 0.813W \*  $42.1^{\circ}$ C/W =  $104.2^{\circ}$ C. This is well below the limit of  $125^{\circ}$ C

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

Table 6. Thermal Resistance  $\theta_{\text{JA}}$  for 48-pin LQFP, Forced Convection

	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

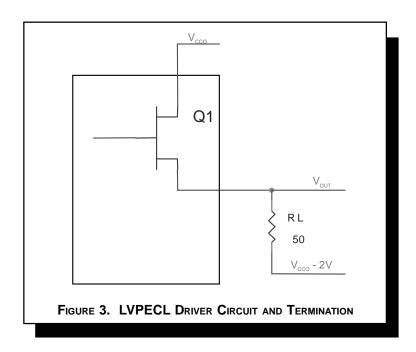
 $\theta_{LA}$  by Velocity (Linear Feet per Minute)

# DIFFERENTIAL-TO-3.3V/2.5V LVPECL CLOCK BUFFER

### 3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in Figure 3.



To calculate worst case power dissipation into the load, use the following equations which assume a  $50\Omega$  load, and a termination voltage of  $V_{CCO}$  - 2V.

• For logic high, 
$$V_{OUT} = V_{OH\_MAX} = V_{CCO\_MAX} - 1.0V$$

$$(V_{CCO\_MAX} - V_{OH\_MAX}) = 1.0V$$

• For logic low, 
$$V_{OUT} = V_{OL\_MAX} = V_{CC\_MAX} - 1.7V$$

$$(V_{CC\_MAX} - V_{OL\_MAX}) = 1.7V$$

Pd\_H is power dissipation when the output drives high.
Pd\_L is the power dissipation when the output drives low.

$$Pd_{-}H = [(V_{OH\_MAX} - (V_{CCO\_MAX} - 2V))/R_{L}] * (V_{CCO\_MAX} - V_{OH\_MAX}) = [(2V - (V_{CCO\_MAX} - V_{OH\_MAX}))/R_{L}] * (V_{CCO\_MAX} - V_{OH\_MAX}) = [(2V - 1V)/50\Omega] * 1V = 20.0mW$$

$$Pd_{L} = [(V_{OL\_MAX} - (V_{CCO\_MAX} - 2V))/R_{L}] * (V_{CCO\_MAX} - V_{OL\_MAX}) = [(2V - (V_{CCO\_MAX} - V_{OL\_MAX}))/R_{L}] * (V_{CCO\_MAX} - V_{OL\_MAX}) = [(2V - 1.7V)/50\Omega] * 1.7V = 10.2mW$$

Total Power Dissipation per output pair = Pd\_H + Pd\_L = 30.2mW

## ICS8537-01

# HEX, LOW SKEW, 1-TO-2 DIFFERENTIAL-TO-3.3V/2.5V LVPECL CLOCK BUFFER

### RELIABILITY INFORMATION

Table 7.  $\theta_{\text{JA}} \text{vs. A} \text{ir Flow Table}$ 

### $\boldsymbol{\theta}_{\text{JA}}$ by Velocity (Linear Feet per Minute)

	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

### TRANSISTOR COUNT

The transistor count for ICS8537-01 is: 1201

# HEX, LOW SKEW, 1-TO-2 DIFFERENTIAL-TO-3.3V/2.5V LVPECL CLOCK BUFFER

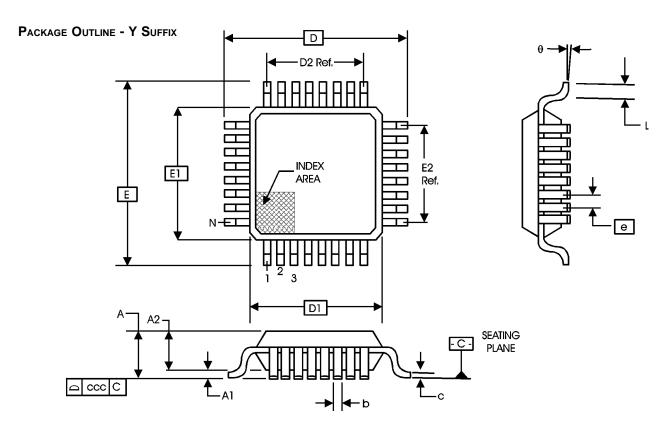


TABLE 8. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS						
CVMDOL		BBC				
SYMBOL	MINIMUM	NOMINAL	MAXIMUM			
N		48				
Α			1.60			
<b>A</b> 1	0.05		0.15			
A2	1.35	1.40	1.45			
b	0.17	0.17 0.22 0.27				
С	0.09	0.09 0.20				
D		9.00 BASIC				
D1		7.00 BASIC				
D2		5.50 Ref.				
E		9.00 BASIC				
E1		7.00 BASIC				
E2		5.50 Ref.				
е		0.50 BASIC				
L	0.45	0.60	0.75			
θ	0°		7°			
ссс			0.08			

Reference Document: JEDEC Publication 95, MS-026



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# HEX, LOW SKEW, 1-TO-2 DIFFERENTIAL-TO-3.3V/2.5V LVPECL CLOCK BUFFER

### TABLE 9. ORDERING INFORMATION

Part/Order Number	Marking	Package	Count	Temperature
ICS8537AY-01	ICS8537AY-01	48 Lead LQFP	250 per tray	0°C to 85°C
ICS8537AY-01T	ICS8537AY-01	48 Lead LQFP on Tape and Reel	1000	0°C to 85°C

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